

# High Performance CMOS Oscillator with Frequency Margining – Pin Control

### **Features**

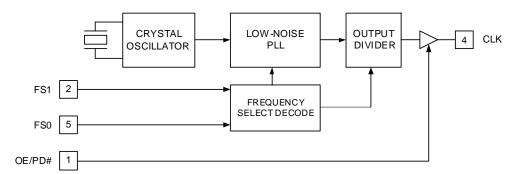
- Crystal oscillator with CMOS output
- Output frequency from 8 MHz to 200 MHz
- Two frequency margining control pins (FS0, FS1)
- Output enable or power-down function
- Factory configured or field programmable
- Integrated phase-locked loop (PLL)
- Supply voltage: 3.3 V or 2.5 V
- Pb-free package: 5.0 x 3.2 mm LCC
- Commercial and industrial temperature ranges

### **Functional Description**

The CY2XF32 is a high performance and high frequency crystal oscillator (XO). It uses a Cypress proprietary low noise PLL to synthesize the frequency from an integrated crystal. The output frequency can be changed via two select pins, allowing easy frequency margin testing in applications.

The CY2XF32 is available as a factory configured device or as a field programmable device.

### Logic Block Diagram





### **Pinouts**

Figure 1. Pin Diagram - 6 Pin Ceramic LCC

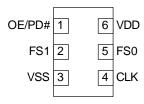


Table 1. Pin Definitions – 6-pin Ceramic LCC

Pin	Name	I/O Type	Description	
1	OE/PD#	CMOS Input	Output Enable or Power-down: Functionality is a programming option; see Table 3 and Table 4 for details.	
2, 5	FS1, FS0	CMOS Input	Frequency Select.	
4	CLK	CMOS Output	Clock Output.	
6	VDD	Power	Supply Voltage: 2.5 V or 3.3 V.	
3	VSS	Power	Ground.	

### **Functional Description**

The FS0 and FS1 pins select between four different output frequencies, as shown in Table 2. Frequency margining is a common application for this feature. One frequency is used for the standard operating mode of the device, while the other frequencies are available for margin testing, either during product development or in system manufacturing test.

**Table 2. Frequency Select** 

FS1	FS0	Output Frequency
0	0	Frequency 0
0	1	Frequency 1
1	0	Frequency 2
1	1	Frequency 3

When changing the output frequency, the frequency transition is not guaranteed to be smooth. There can be frequency excursions beyond the start frequency and the new frequency.

Glitches and runt pulses are possible, and time must be allowed for the PLL to relock.

Pin 1 is programmed to function as either OE (output enable) or PD# (power-down, active low). The OE function is used to enable or disable the CLK output very quickly, but it does not reduce core power consumption. The PD# function puts the device into a low power state, but the wake up takes longer because the PLL must reacquire lock. Details are shown in Table 3 and Table 4.

**Table 3. Output Enable Operation** 

OE	PLL & Xtal Oscillator	Output Buffer
0	Active	Off
1	Active	On

Table 4. Power-down Operation

PD#	PLL & Xtal Oscillator	Output Buffer
0	Off	Off
1	Active	On

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### **Programming Description**

The CY2XF32 is a programmable device. Before being used in an application, it must be programmed with the output frequencies and other variables described in a later section. Two different device types are available, each with its own programming flow. They are described below.

### Field Programmable CY2XF32F

Field programmable devices are shipped unprogrammed and must be programmed before being installed on a printed circuit board (PCB). Customers use CyberClocks™ Online Software to specify the device configuration and generate a JEDEC (extension .jed) programming file. Programming of samples and prototype quantities is available using a Cypress programmer. Third party vendors manufacture programmers for small to large volume applications. Cypress's value added distribution partners also provide programming services. Field programmable devices are designated with an "F" in the part number. They are intended for quick prototyping and inventory reduction. The CY2XF32 is one time programmable (OTP).

The software is located at www.cyberclocksonline.com.

### **Factory Configured CY2XF32**

For ready-to-use devices, the CY2XF32 is available with no field programming required. All requests are submitted to the local Cypress Field Application Engineer (FAE) or sales representative. After the request is processed, the user receives a new part number, samples, and data sheet with the programmed values. This part number is used for additional sample requests and production orders.

### **Programming Variables**

### **Output Frequencies**

The CY2XF32 is programmed with up to four independent output frequencies, which are then selected using the FS0 and FS1 pins. The device can synthesize frequencies to a resolution of one part per million (ppm), but the actual accuracy of the output frequency is limited by the accuracy of the integrated reference crystal.

### Pin 1: Output Enable or Power-down (OE/PD#)

Pin 1 is programmed as either Output Enable (OE) or Power-down (PD#).

### **Supply Voltage**

A programming option optimizes the CY2XF32 for either 2.5 V or 3.3 V supply voltage. A device programmed for a particular supply voltage is not guaranteed to meet specifications when operated at the other voltage.

### **Industrial versus Commercial Device Performance**

Industrial and commercial devices have different internal crystals. This has a potentially significant impact on performance levels for applications requiring the lowest possible phase noise. CyberClocks Online Software displays expected performance for both options.

### **Table 5. Device Programming Variables**

Variable
Output Frequency 0 (Power on default)
Output Frequency 1
Output Frequency 2
Output Frequency 3
Pin 1 Functionality (OE or PD#)
Supply Voltage (2.5 V or 3.3 V)
Temperature Range (Commercial or Industrial)

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### **Absolute Maximum Conditions**

Parameter	Description	Condition	Min	Max	Unit
$V_{DD}$	Supply Voltage		-0.5	4.4	V
$V_{IN}^{[1]}$	Input Voltage, DC	Relative to V <sub>SS</sub>	-0.5	V <sub>DD</sub> +0.5	V
T <sub>S</sub>	Temperature, Storage	Non operating	<b>–</b> 55	135	°C
T <sub>J</sub>	Temperature, Junction		-40	135	°C
ESD <sub>HBM</sub>	ESD Protection (Human Body Model)	JEDEC STD 22-A114-B	2000	_	V
$\Theta_{JA}^{[2]}$	Thermal Resistance, Junction to Ambient	0 m/s airflow	64		°C/W

### **Operating Conditions**

Parameter	Description	Min	Тур	Max	Unit
$V_{DD}$	3.3 V Supply Voltage Range	3.135	3.3	3.465	V
	2.5 V Supply Voltage Range	2.375	2.5	2.625	V
T <sub>PU</sub>	Power-up Time for V <sub>DD</sub> to Reach Minimum Specified Voltage (Power Ramp is Monotonic)	0.05	_	500	ms
T <sub>A</sub>	Ambient Temperature, Commercial	0	_	70	°C
	Ambient Temperature, Industrial	-40	_	85	°C
C <sub>LOAD</sub>	Load Capacitance at CLK (>100 MHz)	_	_	10	pF
	Load Capacitance at CLK (≤100 MHz)	_	_	15	pF

### **DC Electrical Characteristics**

Parameter	Description	Condition	Min	Тур	Max	Unit
I <sub>DD</sub>	Operating Supply Current	$V_{DD}$ = 3.465 V, OE/PD# = $V_{DD}$ , output unloaded	_	-	110	mA
I <sub>SB</sub>	Standby Supply Current	PD# = V <sub>SS</sub>	_	_	200	μΑ
V <sub>OH</sub>	Output High Voltage	$V_{DD} = min, I_{OH} = -4 mA$	0.9 × V <sub>DD</sub>	_	_	V
V <sub>OL</sub>	Output Low Voltage	$V_{DD} = max, I_{OL} = 4 mA$	_	-	0.1 × V <sub>DD</sub>	V
I <sub>OZ</sub>	Output Leakage Current	OE/PD# = V <sub>SS</sub>	-35	-	35	μΑ
V <sub>IH</sub>	Input High Voltage		$0.7 \times V_{DD}$	-	_	V
$V_{IL}$	Input Low Voltage		_	-	0.3 × V <sub>DD</sub>	V
I <sub>IH0</sub>	Input High Current, OE/PD# Pin	Input = V <sub>DD</sub>	_	-	115	μΑ
I <sub>IH1</sub>	Input High Current, FS0 & FS1 Pins	Input = V <sub>DD</sub>	_	-	10	μΑ
I <sub>ILO</sub>	Input Low Current, OE/PD# Pin	Input = V <sub>SS</sub>	-50	-	_	μΑ
I <sub>IL1</sub>	Input Low Current, FS0 & FS1 Pin	Input = V <sub>SS</sub>	-20	-	_	μΑ
C <sub>IN0</sub> [3]	Input Capacitance, OE/PD# Pin		_	15	_	pF
C <sub>IN1</sub> [3]	Input Capacitance, FS0 & FS1 Pin		_	4	_	pF

- The voltage on any input or I/O pin cannot exceed the power pin during power-up.
   Simulated. The board is derived from the JEDEC multilayer standard. It measures 76 x 114 x 1.6 mm and has four layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metalization. No vias are included in the model.
   Not 100% tested, guaranteed by design and characterization.

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## AC Electrical Characteristics<sup>[3]</sup>

Parameter	Description	Condition	Min	Тур	Max	Unit
F <sub>OUT</sub>	Output Frequency <sup>[5]</sup>		8	_	200	MHz
FSC	Frequency Stability, Commercial Devices <sup>[4]</sup>	$T_A = 0$ °C to 70°C	-	_	±35	ppm
FSI	Frequency Stability, Industrial Devices <sup>[4]</sup>	$T_A = -40$ °C to 85°C	-	_	±55	ppm
AG	Aging, 10 Years		_	_	±15	ppm
T <sub>DC</sub>	Output Duty Cycle	Measured at V <sub>DD</sub> /2; see Figure 2	45	50	55	%
T <sub>R</sub>	Output Rise Time	20% to 80% of V <sub>DD</sub> , C <sub>LOAD</sub> = 15 pF	_	0.7	1.5	ns
T <sub>F</sub>	Output Fall Time	80% to 20% of V <sub>DD</sub> , C <sub>LOAD</sub> = 15 pF	_	0.8	1.5	ns
T <sub>OHZ</sub>	Output Disable Time	Time from falling edge on OE to stopped outputs (Asynchronous)	-	_	100	ns
T <sub>OE</sub>	Output Enable Time	Time from rising edge on OE to outputs at a valid frequency (Asynchronous)	-	_	100	ns
T <sub>LOCK</sub>	Startup Time	Time for CLK to reach valid frequency measured from the time $V_{DD} = V_{DD}(min.)$ or from PD# rising edge	_	-	5	ms
T <sub>LFS</sub>	Relock Time	Time for CLK to reach valid frequency from FS0 or FS1 pin change	_	_	1	ms

### Notes

Frequency stability is the maximum variation in frequency from F<sub>0</sub>. It includes initial accuracy, plus variation from temperature and supply voltage.
 This parameter is specified in CyberClocks Online software.



### **Switching Waveforms**

Figure 2. Duty Cycle Timing

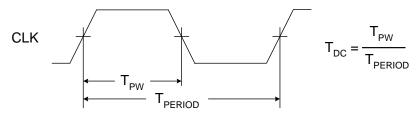


Figure 3. Output Rise and Fall Time

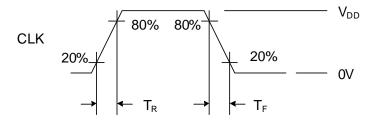
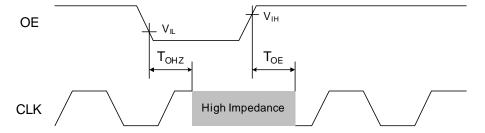


Figure 4. Output Enable and Disable Timing





### **Ordering Information**

The following table contains only the parts that are currently available. If you do not see what you are looking for, contact your local sales representative. For more information, visit the Cypress website at <a href="http://www.cypress.com/products">www.cypress.com/products</a>.

http://www.cypress.com/products.

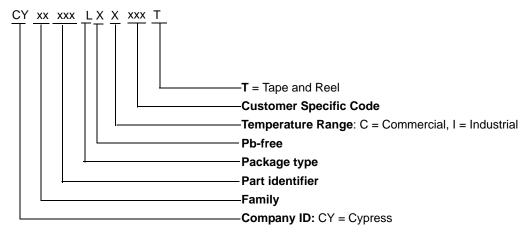
Part Number <sup>[6]</sup> Configuration		Package Description	Product Flow
Pb-free			
CY2XF32FLXCT	Field Programmable	6-Pin Ceramic LCC SMD – Tape and Reel	Commercial, 0° to 70°C
CY2XF32FLXIT	Field Programmable	6-Pin Ceramic LCC SMD – Tape and Reel	Industrial, -40° to 85°C

Some product offerings are factory programmed customer specific devices with customized part numbers. The Possible Configurations table shows the available device types, but not complete part numbers. Contact your local Cypress FAE of Sales Representative for more information.

### **Possible Configurations**

Part Number <sup>[6]</sup> Configuration		Package Description	Product Flow
Pb-free			
CY2XF32LXCxxxT	Factory Configured	6-Pin Ceramic LCC SMD – Tape and Reel	Commercial, 0° to 70°C
CY2XF32LXIxxxT	Factory Configured	6-Pin Ceramic LCC SMD – Tape and Reel	Industrial, –40° to 85°C

### **Ordering Code Definitions**



### Note

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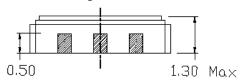
[+] Feedback

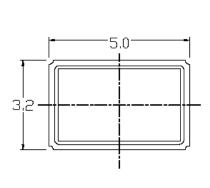
<sup>6. &</sup>quot;xxx" is a factory assigned code that identifies the programming option.

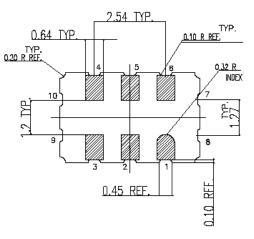


### **Package Diagram**

Figure 5. 6-Pin 3.2 × 5.0 mm Ceramic LCC







Dimensions in mm General Tolerance: ± 0.15MM Kyacara dwg ref KD-VA6432-A Pockage Waight ~ 0.12 grams

001-10044 \*A



### **Acronyms**

Acronym	Description	
CLKOUT	Clock output	
CMOS	Complementary metal oxide semiconductor	
DPM	Die pick map	
EPROM	Erasable programmable read only memory	
LVDS	Low-voltage differential signaling	
NTSC	National television system committee	
OE	Output enable	
PAL	Phase alternate line	
PD	Power-down	
PLL	Phase locked loop	
PPM	Parts per million	
TTL	Transistor transistor logic	

### **Document Conventions**

### **Units of Measures**

Symbol	Unit of Measure	
°C	degrees Celsius	
kHz	kilohertz	
kΩ	kilohms	
MHz	megahertz	
ΜΩ	megaohms	
μΑ	microamperes	
μs	microseconds	
μV	microvolts	
μVrms	microvolts root-mean-square	
mA	milliamperes	
mm	millimeters	
ms	milliseconds	
mV	millivolts	
nA	nanoamperes	
ns	nanoseconds	
nV	nanovolts	
Ω	ohms	



### **Document History Page**

Revision	ECN	Submission Date	Orig. of Change	Description of Change
**	2705753	05/13/09	KVM/PYRS	New data sheet
*A	2734005	07/09/2009	WWZ	Post to external web
*B	2764787	09/19/2009	KVM	Change $I_{SB}$ max from 250 $\mu$ A to 200 $\mu$ A Add max limit for $T_R$ , $T_F$ : 1.5 ns Change $T_{LOCK}$ max from 10 ms to 5 ms Change $T_{LFS}$ max from 10 ms to 1 ms
*C	2958629	06/22/10	KVM	Updated ordering information and package diagram.
*D	3169028	05/06/10	BASH	Changed status from Preliminary to Final. Added Acronyms, Units and Ordering Code Definitions. Updated template as per current Cypress standards.

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